

Image



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
IN RE APPLICATION OF: Peyman Hadizad et al.
FILED: 3/12/2001
FOR: SEMICONDUCTOR COMPONENT AND METHOD OF
MANUFACTURING
Appln. #: 09/802726
Date: 3/2/2004

I HEREBY CERTIFY THAT THE ATTACHED CORRESPONDENCE IS BEING
DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL
IN AN ENVELOPE ADDRESSED TO: COMMISSIONER FOR PATENTS
Alexandria, VA 22313-1450, ON: March 3 2004

Lydia McNamara SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C.
Name of Person Signing Certificate Name of Assignee

Lydia McNamara
SIGNATURE

3/3/04
DATE

**Petition under 37 CFR 1.97(d), CERTIFICATION UNDER 37 CFR
1.97(e), AND DISCLOSURE STATEMENT UNDER 37 CFR 1.56**

Honorable Assistant Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SIR:

Applicants herewith petition the Commissioner of Patents
to consider this information disclosure statement.

Please charge deposit account No. 501086 in the amount of
\$180.00 in accordance with 37 CFR 1.17(p). Any deficiency or
overpayment should be charged or credited to the above stated
deposit account.

Applicants are re-submitting this petition in response to
a PTO-90c communication requesting applicants to include a
separate PTO-1449 form.

Applicants respectfully request that the Examiner
consider the art listed below in the examination of the
subject application and that it be made of record therein.
Applicants previously faxed copies of the below-listed

documents. No warranty is made or implied that an exhaustive search has been conducted or that no other or no more relevant art exists.

I hereby certify that to my knowledge, after reasonable inquiry, no item contained in this information disclosure statement was known to any individual designated in 37 CFR 1.56c more than three months prior to the filing of this information disclosure statement.

1. U.S. Patent No. 6,608,350 B2 issued to Kinzer et al. on August 19, 2003, which discloses a vertical conduction superjunction semiconductor device.
2. U.S. Patent No. 6,509,240 B2 issued on Ren et al, on January 21, 2003, which discloses a method of forming a portion of a superjunction semiconductor device.
3. U.S. Patent No. 6,410,958 B1 issued to Usui et al. on June 25, 2002, which discloses a vertical superjunction semiconductor device.

Respectfully submitted,
Peyman Hadizad et al.



ON Semiconductor
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Form PTO-1449

**LIST OF PATENTS AND PUBLICATIONS
FOR
APPLICANT'S INFORMATION
DISCLOSURE
STATEMENT**
(Use Several Sheets if Necessary)

ATTY. DOCKET NO.

SERIAL NO.

181

APPLICANT

Peyman Hadizad et al.

FILING DATE

3/12/2001

GROUP

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Sub-Class	Filing date (if appropriate)
AA	6 6 0 8 3 5 0	8/19/2003	Kizner et al.			
AB	6 5 0 9 2 4 0	1/21/2003	Ren et al.			
AC	6 4 1 0 9 5 8	6/25/2002	Usui et al.			
AD						
AE						
AF						
AG						
AH						
AI						
AJ						
AK						
AL						
AM						

FOREIGN PATENT DOCUMENTS

Examiner Initial	Document #	Date	Country	Class/subclass	Translation Yes - No
AN					
AO					
AP					
AQ					
AR					

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

AS	
AT	
AU	
AV	
AW	

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance *and* not considered. Include copy of this form with next communication to applicant.